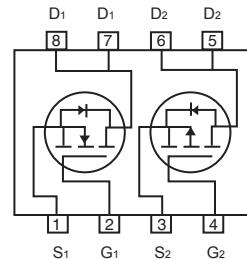
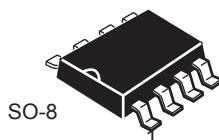


Dual Enhancement Mode Field Effect Transistor (N and P Channel)

FEATURES

5

- 30V, 7A, $R_{DS(ON)} = 28m\Omega$ @ $V_{GS} = 10V$.
 $R_{DS(ON)} = 40m\Omega$ @ $V_{GS} = 4.5V$.
- -30V, -6.2A, $R_{DS(ON)} = 33m\Omega$ @ $V_{GS} = -10V$.
 $R_{DS(ON)} = 52m\Omega$ @ $V_{GS} = -4.5V$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- Surface mount Package.

ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

Parameter	Symbol	N-Channel	P-Channel	Units
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Drain Current-Continuous	I_D	7	-6.2	A
Drain Current-Pulsed ^a	I_{DM}	28	-25	A
Maximum Power Dissipation	P_D	2.0		W
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient ^b	$R_{\theta JA}$	62.5	°C/W



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N-Channel Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$		1		μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
On Characteristics						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		3	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 7\text{A}$		22	28	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 6\text{A}$		30	40	$\text{m}\Omega$
Dynamic Characteristics^d						
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 5\text{V}, I_D = 7\text{A}$		25		S
Input Capacitance	C_{iss}	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		600		pF
Output Capacitance	C_{oss}			140		pF
Reverse Transfer Capacitance	C_{rss}			90		pF
Switching Characteristics^d						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 15\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 2.7\Omega$		8	16	ns
Turn-On Rise Time	t_r			5	10	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			25	50	ns
Turn-Off Fall Time	t_f			5	10	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 15\text{V}, I_D = 5.8\text{A}, V_{\text{GS}} = 10\text{V}$		12	15.9	nC
Gate-Source Charge	Q_{gs}			1.3		nC
Gate-Drain Charge	Q_{gd}			2.3		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current ^b	I_S				1.3	A
Drain-Source Diode Forward Voltage ^c	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 1.3\text{A}$			1.2	V

Notes :

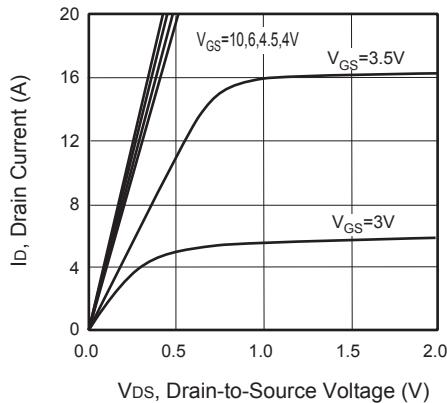
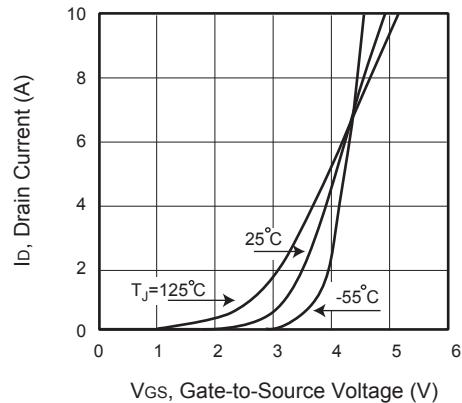
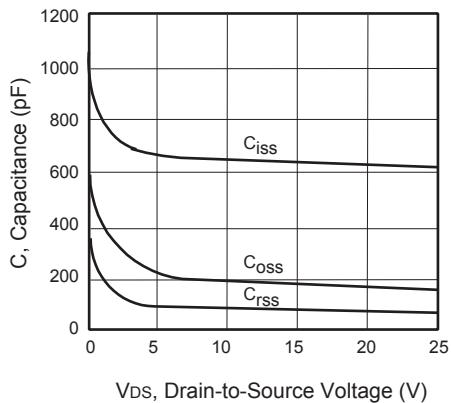
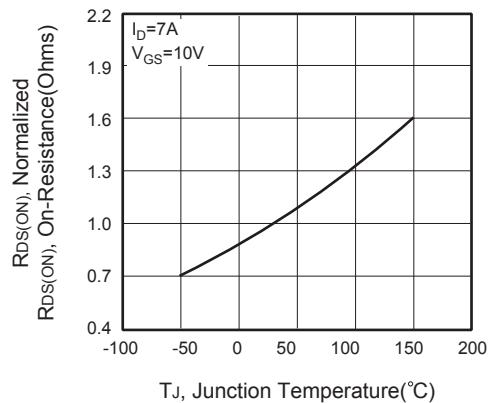
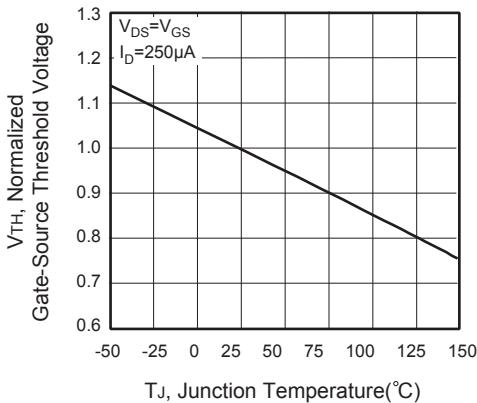
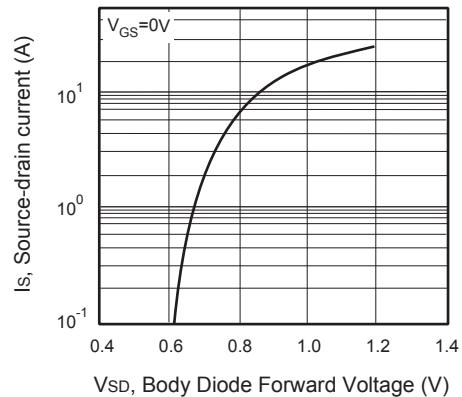
- a.Repetitive Rating : Pulse width limited by maximum junction temperature.□
- b.Surface Mounted on FR4 Board, t ≤ 10 sec.□
- c.Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.□
- d.Guaranteed by design, not subject to production testing.□

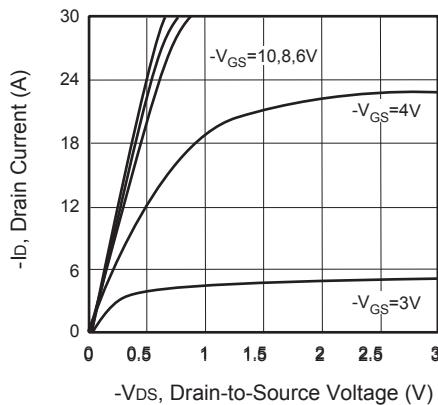
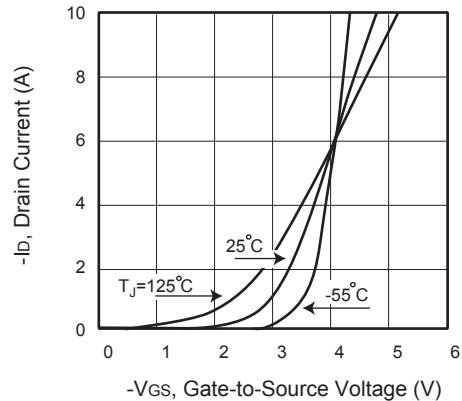
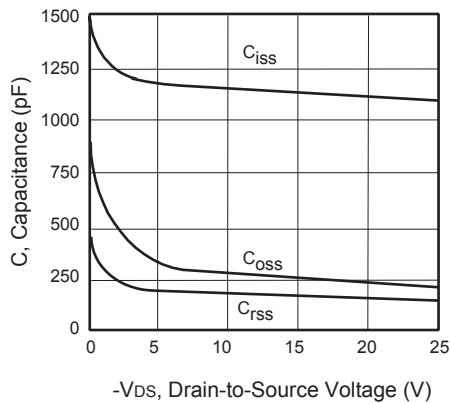
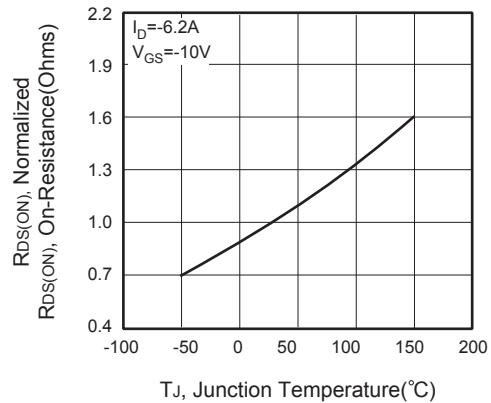
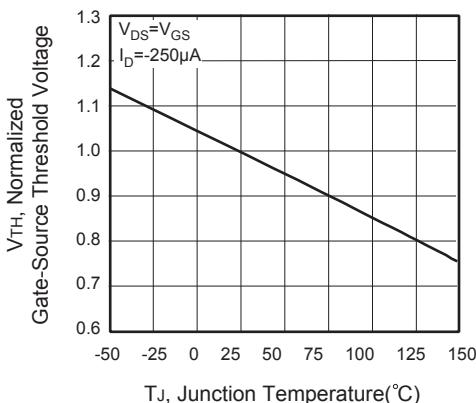
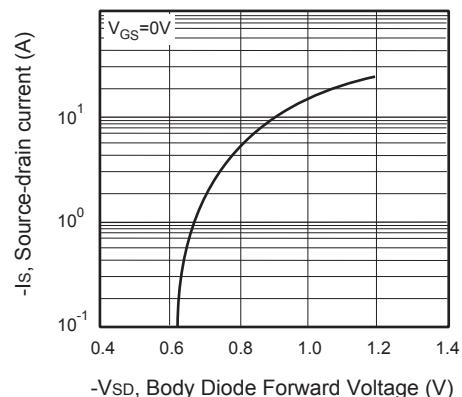


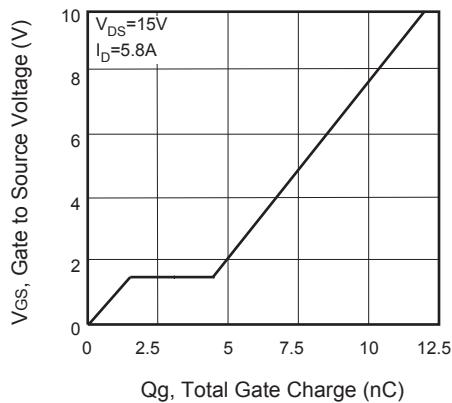
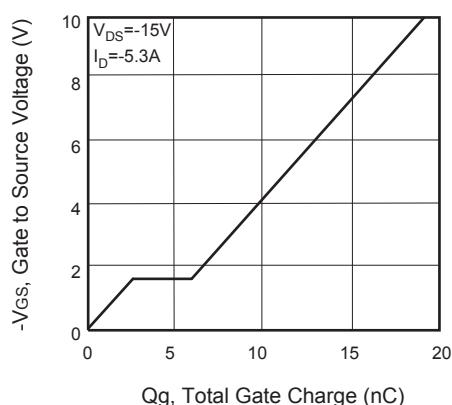
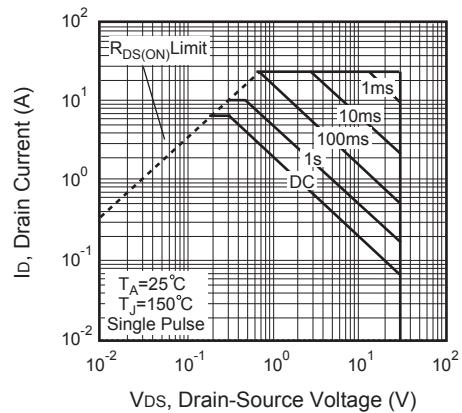
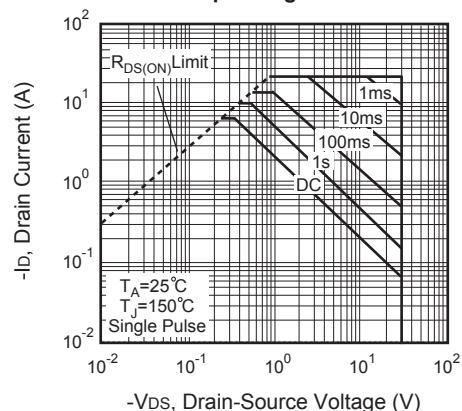
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P-Channel Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = -250\mu\text{A}$	-1		-3	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = -10\text{V}, I_D = -6.2\text{A}$		27	33	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -4\text{A}$		40	52	$\text{m}\Omega$
Dynamic Characteristics^d						
Forward Transconductance	g_{FS}	$V_{\text{DS}} = -10\text{V}, I_D = -6.2\text{A}$		9		S
Input Capacitance	C_{iss}	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		1140		pF
Output Capacitance	C_{oss}			240		pF
Reverse Transfer Capacitance	C_{rss}			140		pF
Switching Characteristics^d						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = -15\text{V}, I_D = -1\text{A}, V_{\text{GS}} = -10\text{V}, R_{\text{GEN}} = 6\Omega$		12	24	ns
Turn-On Rise Time	t_r			5	10	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			57	114	ns
Turn-Off Fall Time	t_f			21	42	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = -15\text{V}, I_D = -5.3\text{A}, V_{\text{GS}} = -10\text{V}$		18.7	24.8	nC
Gate-Source Charge	Q_{gs}			3.7		nC
Gate-Drain Charge	Q_{gd}			2.3		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current ^b	I_S				-1.5	A
Drain-Source Diode Forward Voltage ^c	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = -1\text{A}$			-1.2	V
Notes :						
a.Repetitive Rating : Pulse width limited by maximum junction temperature. b.Surface Mounted on FR4 Board, t ≤ 10 sec. c.Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%. d.Guaranteed by design, not subject to production testing.						

N-CHANNEL**Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Capacitance****Figure 4. On-Resistance Variation with Temperature****Figure 5. Gate Threshold Variation with Temperature****Figure 6. Body Diode Forward Voltage Variation with Source Current**

P-CHANNEL

Figure 7. Output Characteristics

Figure 8. Transfer Characteristics

Figure 9. Capacitance

Figure 10. On-Resistance Variation with Temperature

Figure 11. Gate Threshold Variation with Temperature

Figure 12. Body Diode Forward Voltage Variation with Source Current

N-CHANNEL**Figure 13. Gate Charge****P-CHANNEL****Figure 15. Gate Charge****Figure 14. Maximum Safe Operating Area****Figure 16. Maximum Safe Operating Area**

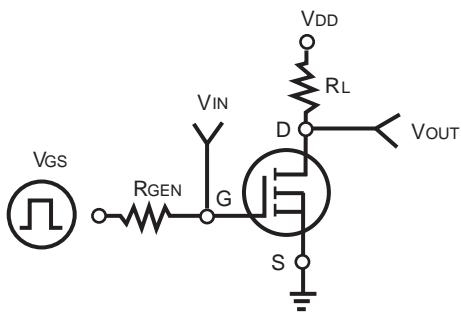


Figure 17. Switching Test Circuit

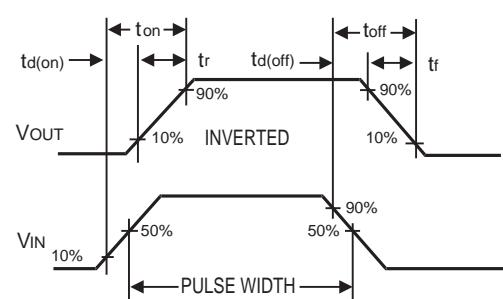


Figure 18. Switching Waveforms

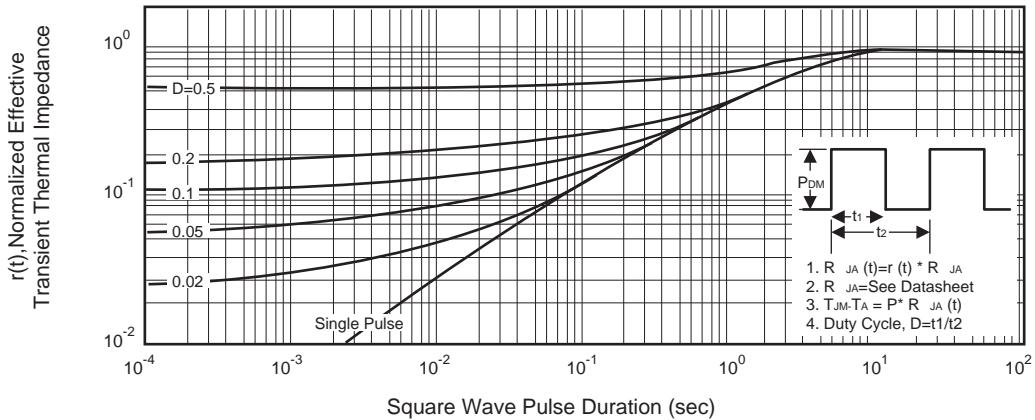


Figure 19. Normalized Thermal Transient Impedance Curve